

## CLAIMS

What is claimed is:

- 1 *Sub 1* 1. A composite heat sink device for surface mounting to a circuit board,  
2 said device comprising:  
3 a heat sink body consisting essentially of aluminum, said body comprising at  
4 least one mounting land with a substantially planar surface, and  
5 a thermally conductive solderable element mechanically fixed to each said  
6 mounting land, each said element having a first planar surface which is contiguous with at least  
7 one said planar surface of said heat sink body and an opposed second planar surface for  
8 soldering to said circuit board.
- 9 2. A composite heat sink device as in claim 1 wherein said heat sink body  
10 has two of said lands, said substantially planar surfaces being coplanar.
- 11 3. A composite heat sink device as in claim 2 wherein said body comprises  
12 a heat dissipating fin upstanding from each of said lands, and a bight upstanding from said  
13 lands between said fins.
- 14 4. A composite heat sink device as in claim 3 wherein said bight has a  
15 planar section which is parallel to said lands and intended to be arranged over an electronic  
16 device on said circuit board.
- 17 5. A composite heat sink device as in claim 1 wherein said heat sink body is  
18 formed from a sheet of aluminum.
- 19 6. A composite heat sink device as in claim 5 wherein said heat sink body is  
20 formed from a sheet of anodized aluminum.

1                   7.     A composite heat sink device as in claim 6 wherein said anodized  
2 aluminum is blackened.

1                   8.     A composite heat sink device as in claim 1 wherein said heat sink body is  
2 extruded.

1                   9.     A composite heat sink device as in claim 1 wherein said element is  
2 mechanically fixed to said land by providing at least one projection on said land, providing at  
3 least one socket in each said element, and inserting each said projection into a respective at  
4 least one socket in an interference fit.

                  10.    A composite heat sink device as in claim 9 wherein the element is  
swaged onto the land.

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